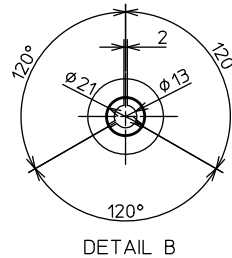
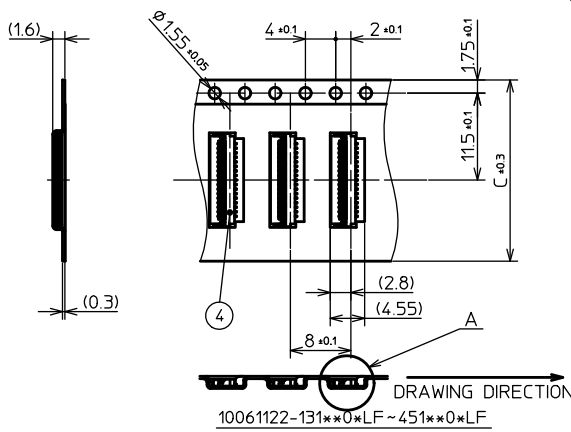
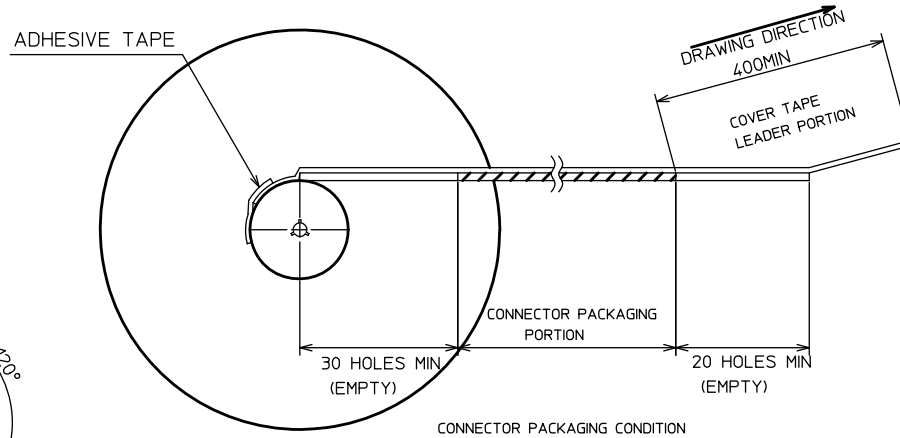
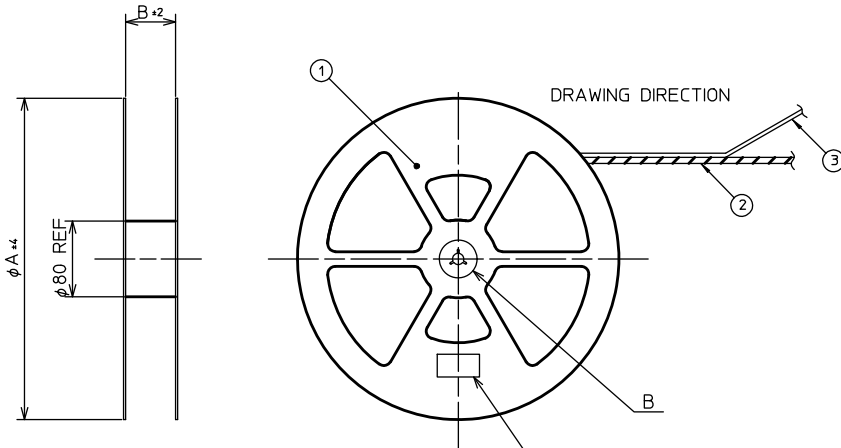


PRODUCT NO

10061122-**-**1**0*LF

EMBOSS TAPE	DIMENSIONS		
	φ A	B	C
10061122-131**0*LF~451**0*LF	φ330	25.5	24
10061122-511**0*LF~		33.5	32

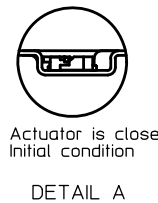
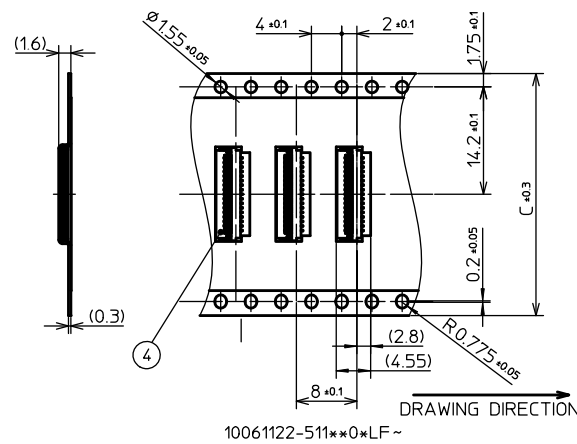
PT.NO.	PARTS NAME	PRODUCT NO.	MATERIAL	Q'TY	NOTE
1	REEL		POLYSTYRENE	1	COLOR:WHITE,ELECTRIFICATION PREVENTION PROCESSING
2	EMBOSS TAPE		PP OR PET	1	ELECTRIFICATION PREVENTION PROCESSING
3	COVER TAPE		POLYESTER		
4	CONNECTOR	10061122-**-**1**0*LF	10061122 SHEET 2,3	5000	
		10061122-**-**1**HLF	10061122 SHEET 4,5		



NOTE
 1.THIS ARTICLE CARRIES OUT THE EMBOSS TAPE PACKAGE OF THE P/N10061122 SERIES CONNECTOR
 2.THE SHAPE AND DIMENSION OF THIS ARTICLE ARE BASED ON JIS C 0806 (TAPING OF ELECTRONIC PARTS(SURFACE MOUNTED DEVICE))

P/N COMPOSITION
 10061122-**-**1**0*LF

- 1: NONE-HALOGEN-FREE-RESIN
- 2: HALOGEN FREE RESIN
- LEAD FREE
- PACKAGING FORM (E-PLASTIC REEL/EMBOSS TAPE PACKAGE)
- EMBOSSING TAPE PACKAGE 0: 8mm PITCH
- PLATING SPEC 1: AU PLATING
- MOUNTING
 - 1: SMT/WITH CABLE LOCK
 - 2: SMT/WITHOUT CABLE LOCK
 - 3: SMT/WITH CABLE LOCK/WITH ACTUATOR LOCK
 - 4: SMT/WITHOUT CABLE LOCK/WITH ACTUATOR LOCK
- CONTACT SIDE 1: DOWN SIDE
- NO OF POSITION
- SERIES NAME

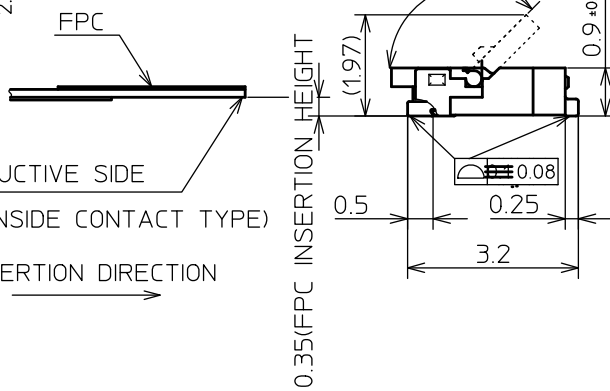
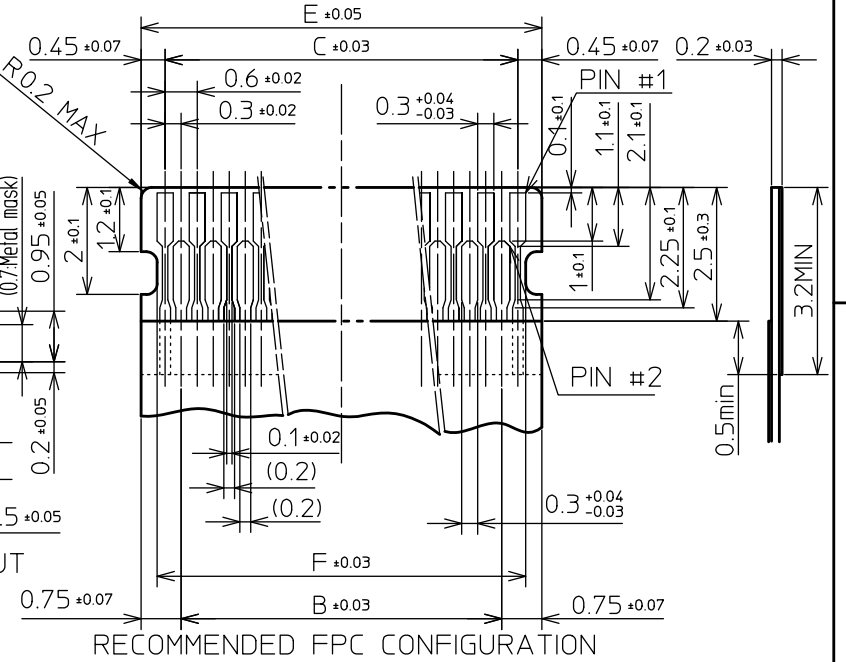
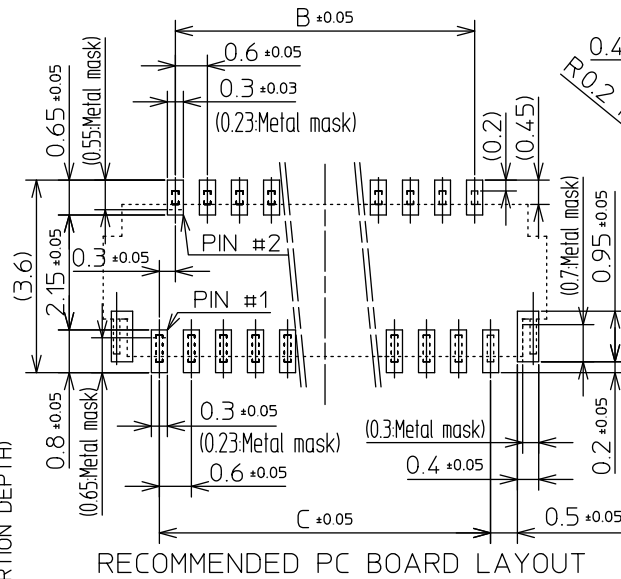
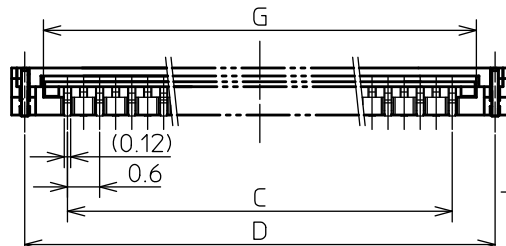
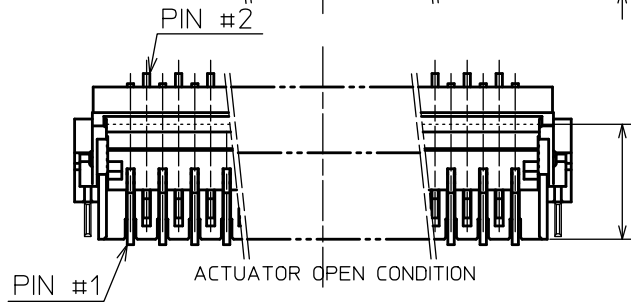
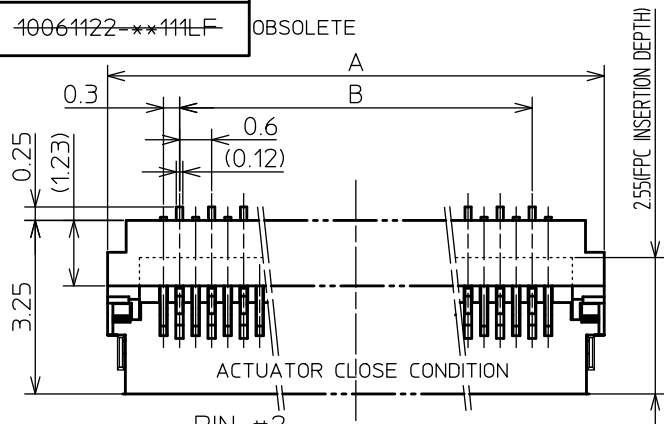


mat'l. code		surface		tolerance		projection	product family		CODE	
		ISO 1302	ISO 406	ISO 101			587F (YLL-D)		JP	
lfr	description	ech no	dr	date	tolerances unless otherwise specified		MM	title		
T	REVISED	ELX-J-20610	TJ	2015-04-17	angles	linear		±0.3	0.3mm PITCH FPC CONNECTOR	
S	REVISED	ELX-J-14161	TJ	2013-03-05	±3	scale	MM	DOWN CONTACT TYPE ET PACKAGING		
R	REVISED	ELX-J-0246	TJ	2012-08-31				product family		587F (YLL-D)
P	REVISED	J10-0280	TJ	2011-12-14	drawing		dwg no		sheet of	size
N	REVISED	J10-0268	TJ	2010-10-12	engr		10F37		A2	
M	REVISED	J10-0185	TJ	2010-07-06	chr		10061122			
L	REVISED	J10-0073	TJ	2010-05-17	appd		type		Product	Customer
sheet	revision	T	N	G	A	C	C	Drawing		Rev.
index	1	2	3	4	5	6	7			T

PRODUCT NO.

40061122-**-**111LF

OBSOLETE



NOTE

- MATERIAL
 - HOUSING: THERMOPLASTIC RESIN, UL94V-0, NATURAL
 - ACTUATOR: THERMOPLASTIC RESIN, UL94V-0, BLACK
 - CONTACT: COPPER ALLOY
 - FIXING TAB: COPPER ALLOY
- FINISH
 - CONTACT: ALL OVER Ni (WITH Ni BARRIER) (CONTACT AREA) Au (SOLDER TAIL AREA) Au
 - FIXING TAB: ALL OVER Ni Sn PLATING
- CO-PLANARITY: ~~0.127~~ 0.08 MAX
- THICKNESS OF A METAL MASK: 0.1mm
- FPC

ADHESIVE METHOD OF SUPPORTING TAP SHALL BE HEAT CRIMPING METHOD AND THERMOSETTING ADHESIVE MATERIAL SHALL BE USED.
- PRODUCT

RECOMMENDED PCB LAYOUT AND FPC AREA THE SAME AS 10064555-**-**2110ELFY(LL-UPPER CONTACT TYPE)
- OTHER

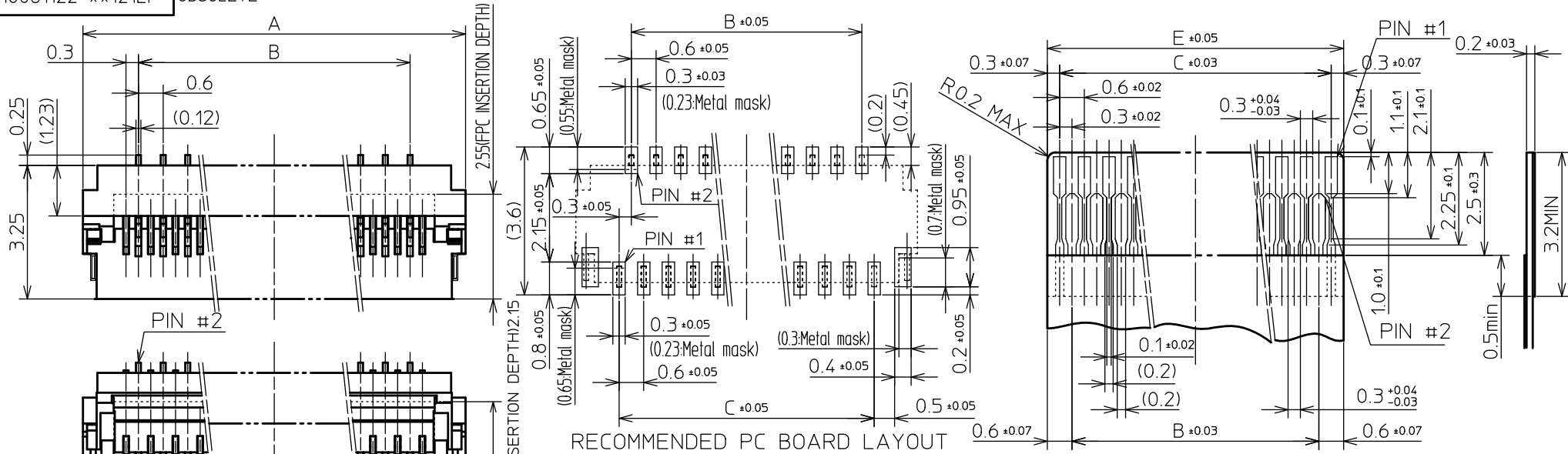
THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008

P/N	A	B	C	D	E	F	G	
40061122-13111LF	5.7	3.0	3.6	5.2	4.5	3.9	4.53	OBSOLETE
40061122-15111LF	6.3	3.6	4.2	5.8	5.1	4.5	5.13	OBSOLETE
40061122-17111LF	6.9	4.2	4.8	6.4	5.7	5.1	5.73	OBSOLETE
40061122-21111LF	8.1	5.4	6.0	7.6	6.9	6.3	6.93	OBSOLETE
40061122-23111LF	8.7	6.0	6.6	8.2	7.5	6.9	7.53	OBSOLETE
40061122-25111LF	9.3	6.6	7.2	8.8	8.1	7.5	8.13	OBSOLETE
40061122-33111LF	11.7	9.0	9.6	11.2	10.5	9.9	10.53	OBSOLETE
40061122-35111LF	12.3	9.6	10.2	11.8	11.1	10.5	11.13	OBSOLETE
40061122-39111LF	13.5	10.8	11.4	13.0	12.3	11.7	12.33	OBSOLETE
40061122-41111LF	14.1	11.4	12.0	13.6	12.9	12.3	12.93	OBSOLETE

mat'l. code		surface		tolerance		projection		product family		CODE	
		ISO 1302		ISO 406 ISO 1101		MM		587F		JP	
ltr		description		ecn no		date		title			
N		REVISED		ELX-J-01245-1		T.I		0.3mm PITCH FPC CONNECTOR			
M		REVISED		J11-0280		T.I		DOWN CONTACT TYPE			
L		REVISED		J10-0185		T.I					
K		REVISED		J08-0430		K.O					
J		REVISED		J08-0315		K.O					
H		REVISED		J08-0189		K.O					
G		REVISED		J07-0399		K.O					
sheet		revision						dwg no		sheet of	
index		sheet						10061122		2 of 7	
								type		Product Customer Drawing	
								Rev.		N	

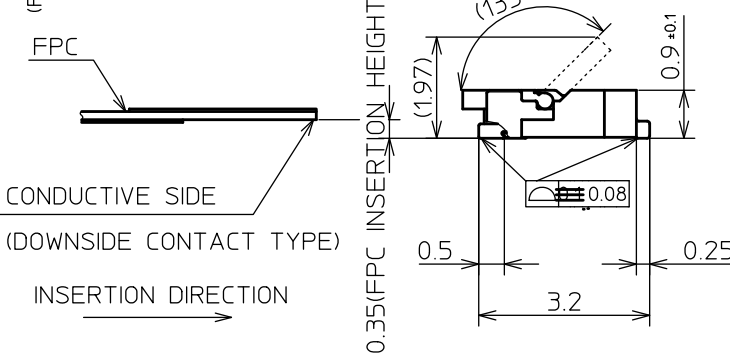
PRODUCT NO.

40064122-***121LF OBSOLETE



NOTE

- MATERIAL
 - HOUSING: THERMOPLASTIC RESIN, UL94V-0, NATURAL
 - ACTUATOR: THERMOPLASTIC RESIN, UL94V-0, BLACK
 - CONTACT: COPPER ALLOY
 - FIXING TAB: COPPER ALLOY
- FINISH
 - CONTACT: ALL OVER Ni (WITH Ni BARRIER)
(CONTACT AREA) Au
(SOLDER TAIL AREA) Au
 - FIXING TAB: ALL OVER Ni
Sn PLATING
- CO-PLANARITY: 0.08 MAX
- THICKNESS OF A METAL MASK: 0.1mm
- FPC
ADHESIVE METHOD OF SUPPORTING TAP SHALL BE HEAT CRIMPING METHOD AND THERMOSETTING ADHESIVE MATERIAL SHALL BE USED.
- PRODUCT
RECOMMENDED PCB LAYOUT AND FPC AREA THE SAME AS 10064555-***2210ELFY (LL-UPPER CONTACT TYPE)
- OTHER
THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008

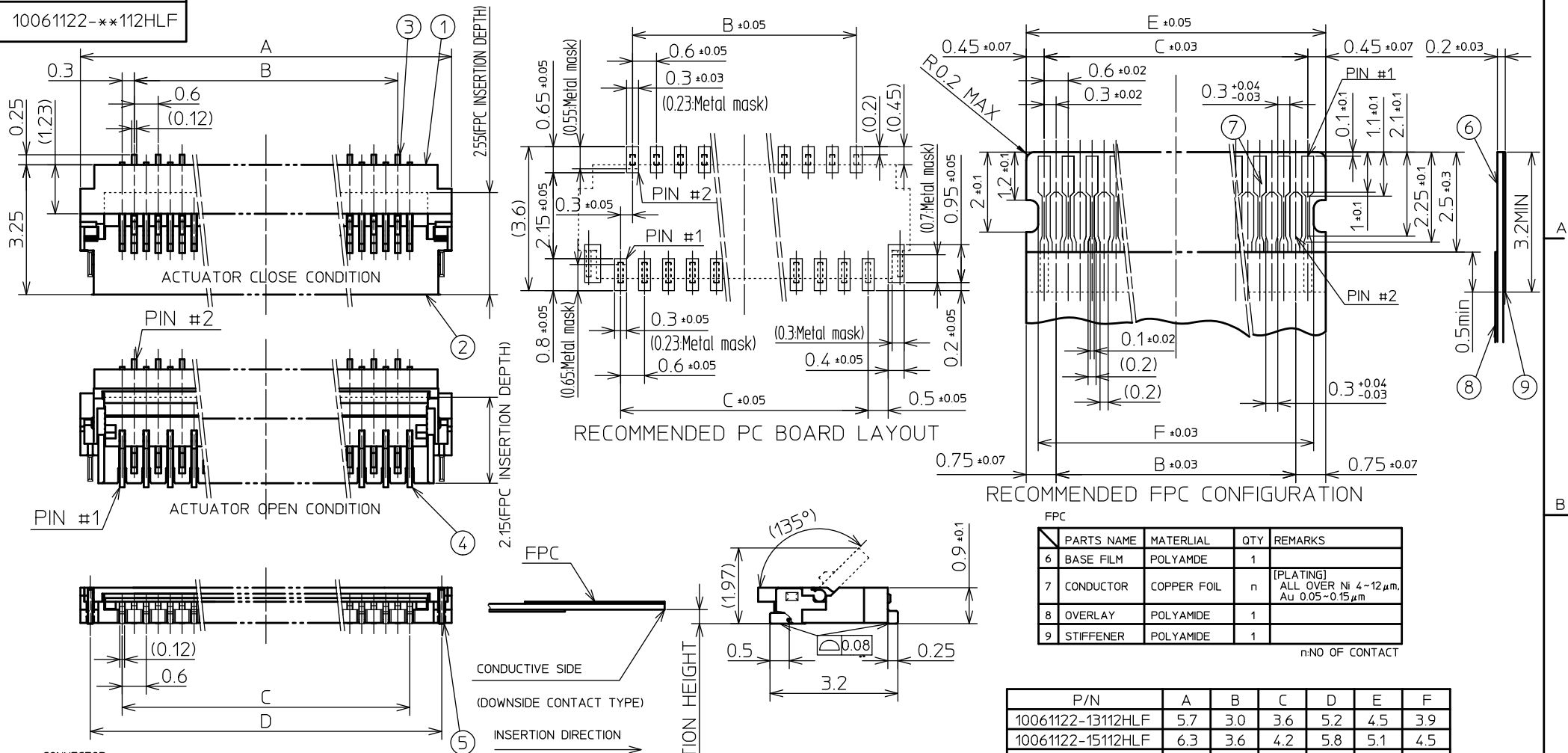


P/N	A	B	C	D	E	
40064122-45121LF	6.3	3.6	4.2	5.8	4.8	OBSOLETE
40064122-24121LF	8.1	5.4	6.0	7.6	6.6	OBSOLETE
40064122-23121LF	8.7	6.0	6.6	8.2	7.2	OBSOLETE
40064122-25121LF	9.3	6.6	7.2	8.8	7.8	OBSOLETE
40064122-33121LF	11.7	9.0	9.6	11.2	10.2	OBSOLETE
40064122-35121LF	12.3	9.6	10.2	11.8	10.8	OBSOLETE
40064122-37121LF	12.9	10.2	10.8	12.4	11.4	OBSOLETE
40064122-39121LF	13.5	10.8	11.4	13.0	12.0	OBSOLETE
40064122-41121LF	14.1	11.4	12.0	13.6	12.6	OBSOLETE
40064122-43121LF	14.7	12.0	12.6	14.2	13.2	OBSOLETE
40064122-45121LF	15.3	12.6	13.2	14.8	13.8	OBSOLETE

mat'l. code				surface ISO 1302		tolerance ISO 406 ISO 1101		projection		product family 587F		CODE JP
ltr	description	ecn no	dr	date	tolerances unless otherwise specified			title		0.3mm PITCH FPC CONNECTOR DOWN CONTACT TYPE		
G	REVISED	ELX-J-01245-1	T.I	2012-08-31	angles	linear	±0.2	MM		dwg no 10061122 sheet of 3 of 37 size A3		
F	REVISED	J11-0280	T.I	2011-12-14				scale		type Product Customer Drawing		
E	REVISED	J10-0185	T.I	2010-7-6						Rev. G		
D	REVISED	J10-0073	T.I	2010-5-17	dr	TISHISHITA		2012-08-31				
C	REVISED	J08-0430	K.O	2008-11-10	enrg	H.Suzuki		2012-08-31				
B	REVISED	J08-0189	K.O	2008-4-28	chr	M.Kajiura		2012-08-31				
A	RELEASED	J07-0399	K.O	28/Sep/07	apdd							
sheet index	revision sheet											

PRODUCT NO.

10061122-**112HLF



FPC				
NO	PARTS NAME	MATERIAL	QTY	REMARKS
6	BASE FILM	POLYAMIDE	1	
7	CONDUCTOR	COPPER FOIL	n	[PLATING] ALL OVER Ni 4~12μm, Au 0.05~0.15μm
8	OVERLAY	POLYAMIDE	1	
9	STIFFENER	POLYAMIDE	1	

n:NO OF CONTACT

P/N	A	B	C	D	E	F
10061122-13112HLF	5.7	3.0	3.6	5.2	4.5	3.9
10061122-15112HLF	6.3	3.6	4.2	5.8	5.1	4.5
10061122-17112HLF	6.9	4.2	4.8	6.4	5.7	5.1
10061122-21112HLF	8.1	5.4	6.0	7.6	6.9	6.3
10061122-23112HLF	8.7	6.0	6.6	8.2	7.5	6.9
10061122-25112HLF	9.3	6.6	7.2	8.8	8.1	7.5

*For the corresponding position, please make an inquire to sales person in our company.

CONNECTOR				
NO	PARTS NAME	MATERIAL	QTY	REMARKS
1	HOUSING	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0.COLOR:BLACK
2	ACTUATOR	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0.COLOR:NATURAL
3	CONTACT A	COPPER ALLOY	(n-1)/2	[PLATING] ALL OVER Ni(WITH Ni BARRIER) CONTACT AREA: Au SOLDER TAIL AREA: Au
4	CONTACT B	COPPER ALLOY	(n+1)/2	
5	FIXING TAB	COPPER ALLOY	2	[PLATING] ALL OVER Ni,Sn

n:NO OF CONTACT

NOTE

1.CO-PLANARITY:0.08mmMAX

2.THICKNESS OF A METAL MASK:0.1mm

3.FPC

Adhesive method of supporting tape shall be heat crimping method and thermosetting adhesive material shall be used.

4.PRODUCT

Recommended PCB layout and FPC area the same as 10064555-**2110*LF(YLL-Upper contact type)

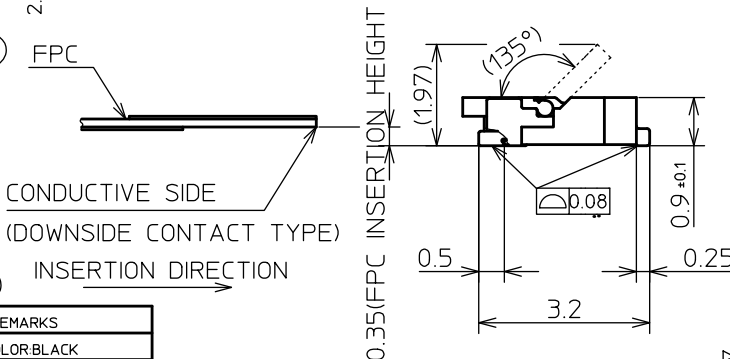
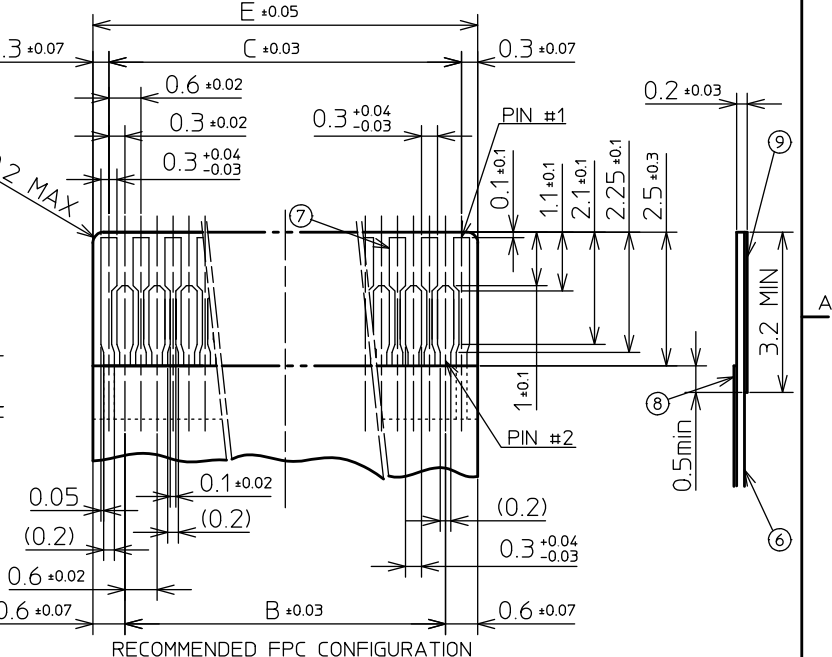
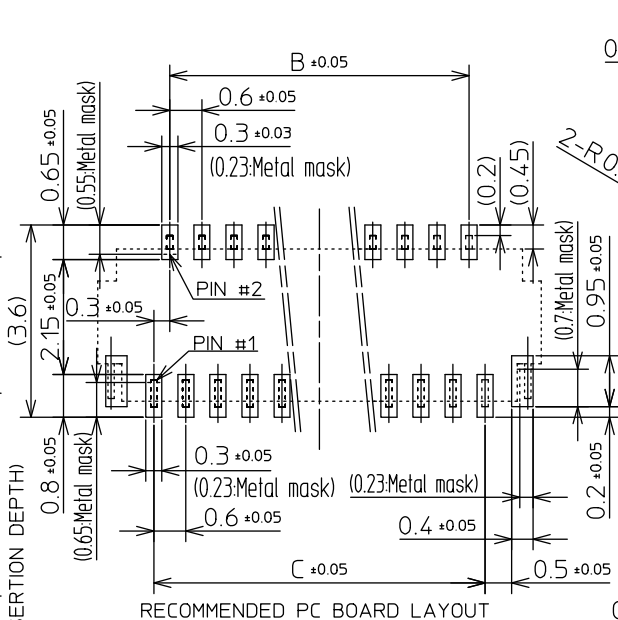
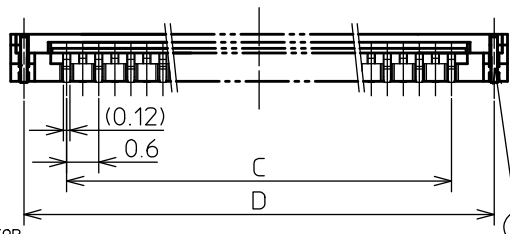
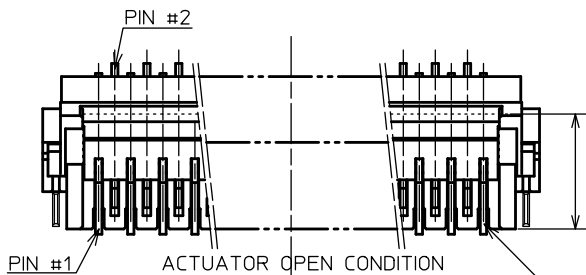
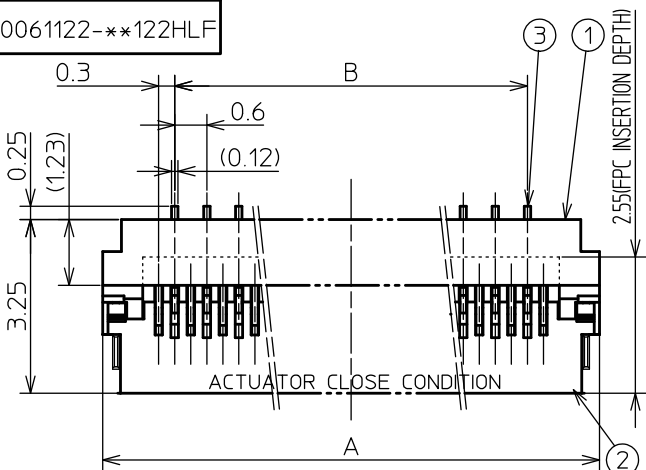
5.OTHER

This product meets European Union Directives and other country regulation as described in GS-22-008

mat'l. code		surface		tolerance		projection		product family		CODE	
		ISO 1302		ISO 406 ISO 1101				587F (YLL-D)		JP	
l/r		description		ecn no		dr		date		title	
A		Released		J10-0185		T.I.		2010-07-06		0.3mm PITCH FPC CONNECTOR DOWN CONTACT TYPE	
		angles		linear		±0.2		MM		scale	
		±2'									
		dr		T.ISHISHITA		2010-07-06				dwg no	
		enr		Y.Kameda		2010-07-06				sheet of	
		chr		M.Kajiura		2010-07-06				10061122	
		appd								4 of 7	
sheet		revision								size	
index		sheet								A3	
										type Product Customer Drawing	
										Rev. A	

PRODUCT NO

10061122-**-**122HLF



FPC			
PARTS NAME	MATERIAL	QTY	REMARKS
6	BASE FILM	POLYAMDE	1
7	CONDUCTOR	COPPER FOIL	n [PLATING] ALL OVER Ni 4~12 μm, Au 0.05~0.15 μm
8	OVERLAY	POLYAMIDE	1
9	STIFFENER	POLYAMIDE	1

n: NO OF CONTACT

P/N	A	B	C	D	E
10061122-15122HLF	6.3	3.6	4.2	5.8	4.8
10061122-21122HLF	8.1	5.4	6.0	7.6	6.6
10061122-23122HLF	8.7	6.0	6.6	8.2	7.2
10061122-25122HLF	9.3	6.6	7.2	8.8	7.8

*For the corresponding position, please make an inquire to sales person in our company.

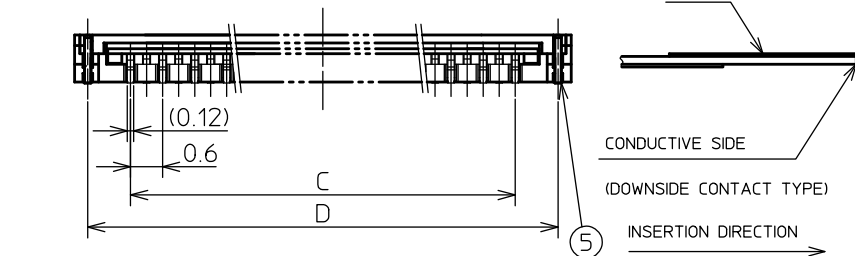
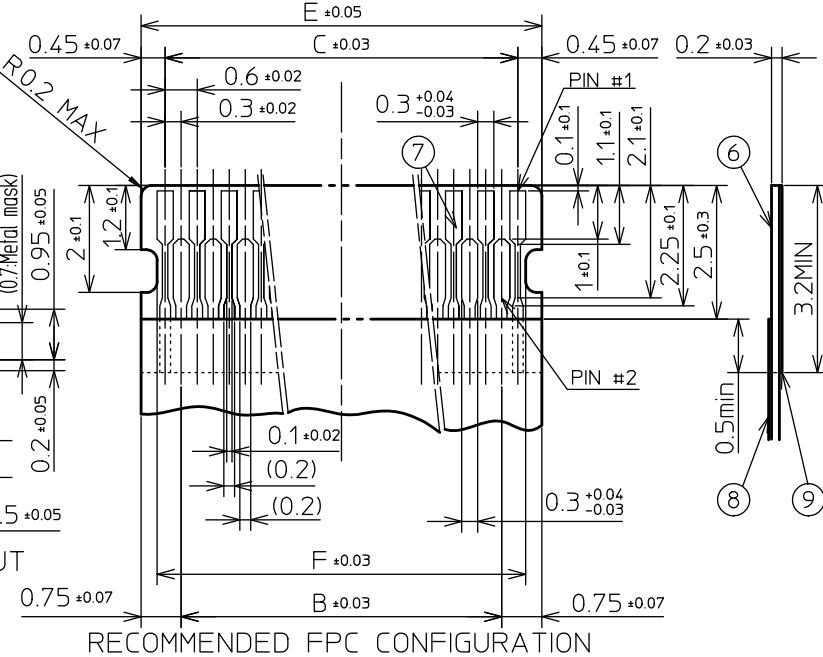
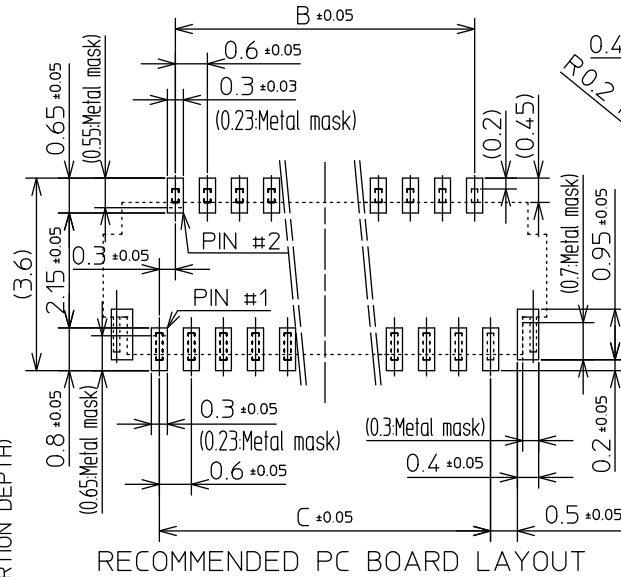
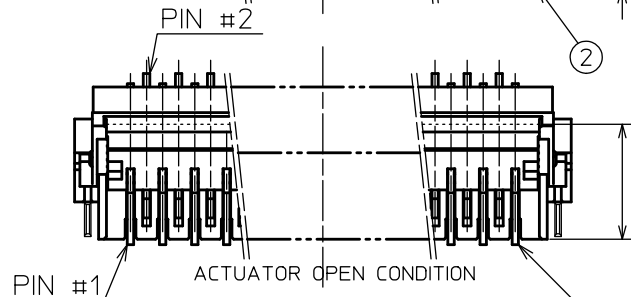
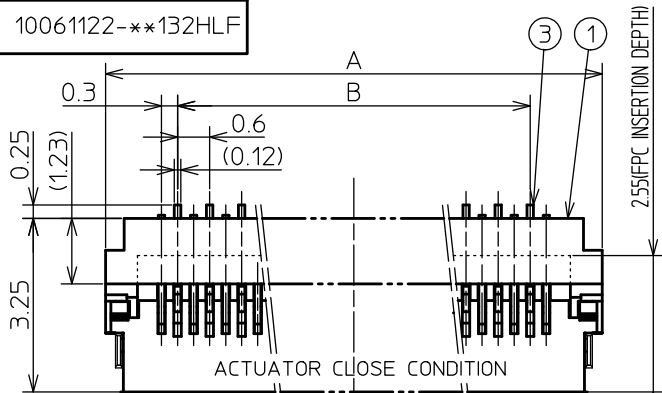
CONNECTOR					
PARTS NAME	MATERIAL	QTY	REMARKS		
1	HOUSING	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:BLACK	
2	ACTUATOR	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:NATURAL	
3	CONTACT A	COPPER ALLOY	(n-1)/2	[PLATING] ALL OVER Ni(WITH Ni BARRIER) CONTACT AREA:Au SOLDER TAIL AREA:Au	n:NO OF CONTACT
4	CONTACT B	COPPER ALLOY	(n+1)/2	[PLATING] ALL OVER Ni,Sn	
5	FIXING TAB	COPPER ALLOY	2	[PLATING] ALL OVER Ni,Sn	

NOTE
 1.CO-PLANARITY:0.08mmMAX
 2.THICKNESS OF A METAL MASK:0.1mm
 3.FPC
 Adhesive method of supporting tape shall be heat crimping method and thermosetting adhesive material shall be used.
 4.PRODUCT
 Recommended PCB layout and FPC area the same as 10064555-**-**2110*LF(YLL-Upper contact type)
 5.OTHER
 This product meets European Union Directives and other country regulation as described in GS-22-008

mat'l. code		surface ISO 1302		tolerance ISO 406 ISO 1101		projection		product family		CODE JP	
lfr	description	ecn no	dr	date	tolerances unless otherwise specified		MM	587F (YLL-D)		title	
A	Released	J10-0185	T.I	2010-07-06	± 0.2			0.3mm PITCH FPC CONNECTOR DOWN CONTACT TYPE			
B	Revised	ELX-J-12415	T.I	2012-08-31	angles linear		scale	dwg no		sheet of size	
C	Revised	ELX-J-20618	T.I	2015-04-17	± 2'			10061122		5of7 A3	
sheet index		revision sheet		dr		engr		type		Product Customer Drawing	
				T.ISHISHITA		M.Minato		Rev.		C	
				2015-04-17		N.Sasame					

PRODUCT NO.

10061122-**132HLF



PARTS NAME	MATERIAL	QTY	REMARKS
6	BASE FILM	POLYAMDE	1
7	CONDUCTOR	COPPER FOIL	n [PLATING] ALL OVER Ni 4~12µm, Au 0.05~0.15µm
8	OVERLAY	POLYAMIDE	1
9	STIFFENER	POLYAMIDE	1

n: NO OF CONTACT

P/N	A	B	C	D	E	F
10061122-27132HLF	9.9	7.2	7.8	9.4	8.7	8.1
10061122-29132HLF	10.5	7.8	8.4	10.0	9.3	8.7
10061122-33132HLF	11.7	9.0	9.6	11.2	10.5	9.9
10061122-35132HLF	12.3	9.6	10.2	11.8	11.1	10.5
10061122-39132HLF	13.5	10.8	11.4	13.0	12.3	11.7
10061122-41132HLF	14.1	11.4	12.0	13.6	12.9	12.3
10061122-45132HLF	15.3	12.6	13.2	14.8	14.1	13.5

PARTS NAME	MATERIAL	QTY	REMARKS
1 HOUSING	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:BLACK
2 ACTUATOR	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:NATURAL
3 CONTACT A	COPPER ALLOY	(n-1)/2	[PLATING] ALL OVER Ni(WITH Ni BARRIER) CONTACT AREA: Au SOLDER TAIL AREA: Au
4 CONTACT B	COPPER ALLOY	(n+1)/2	[PLATING] ALL OVER Ni,Sn
5 FIXING TAB	COPPER ALLOY	2	[PLATING] ALL OVER Ni,Sn

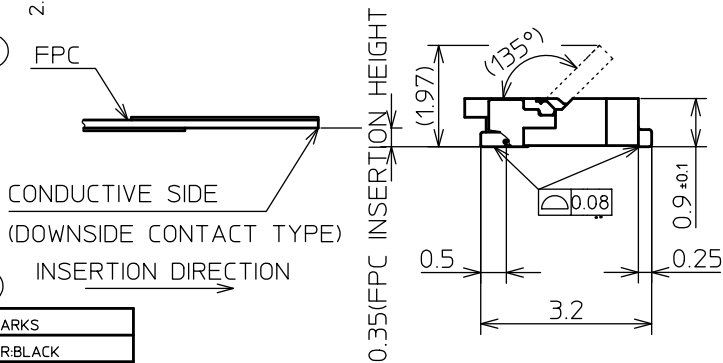
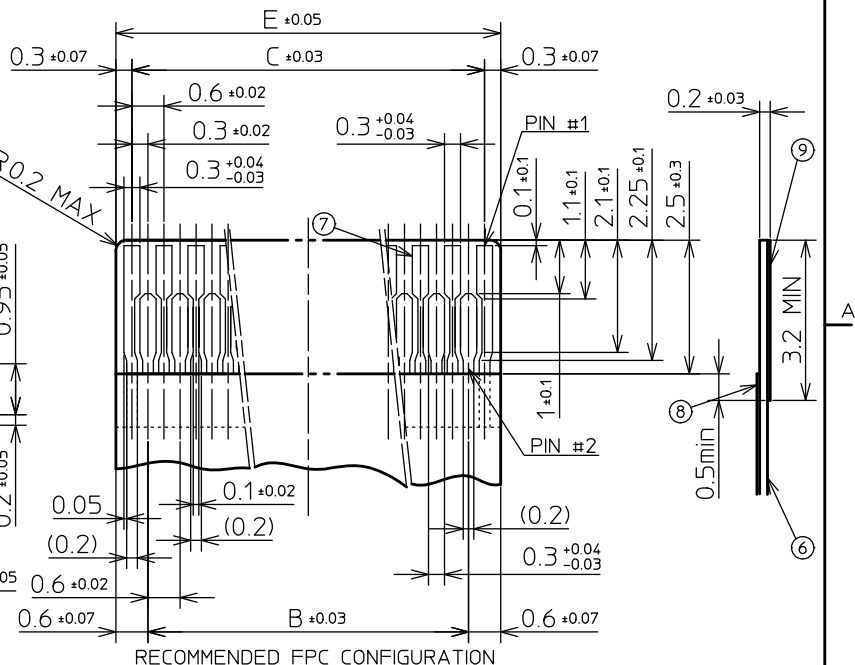
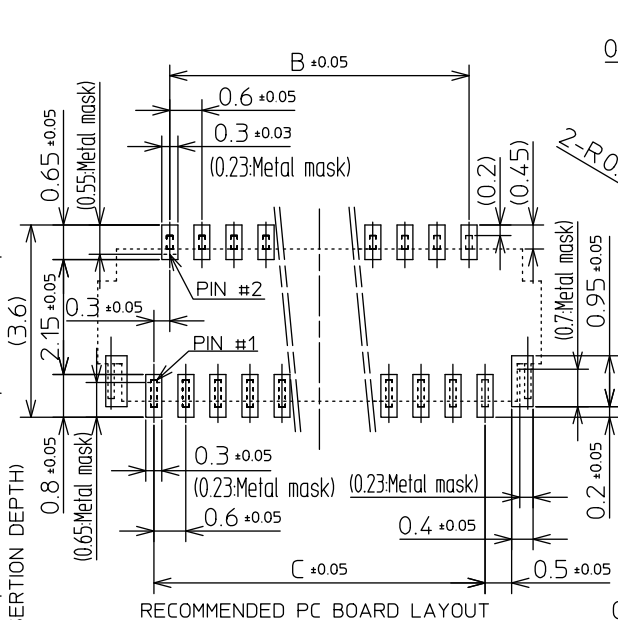
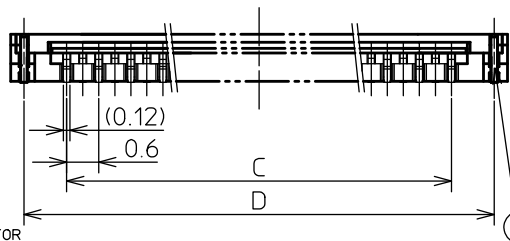
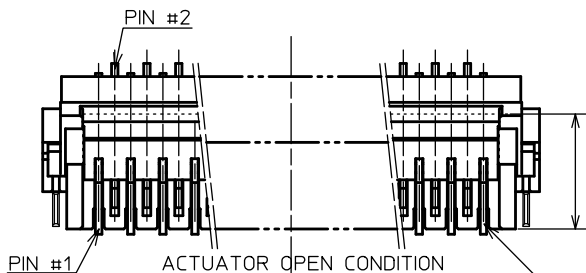
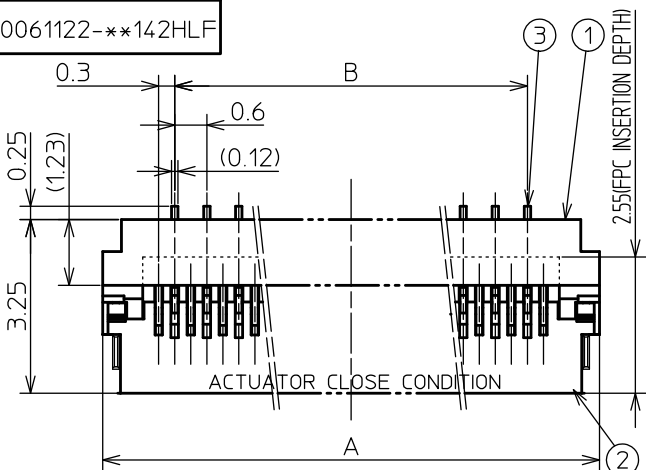
n: NO OF CONTACT

NOTE
 1.CO-PLANARITY:0.08mmMAX
 2.THICKNESS OF A METAL MASK:0.1mm
 3.FPC
 Adhesive method of supporting tape shall be heat crimping method and thermosetting adhesive material shall be used.
 4.PRODUCT
 Recommended PCB layout and FPC area the same as 10064555-**2110*LF(YLL-Upper contact type)
 5.OTHER
 This product meets European Union Directives and other country regulation as described in GS-22-008

mat'l. code		surface ISO 1302		tolerance ISO 406 ISO 1101		projection		product family 587F (YLL-D)		CODE JP	
ltr	description	ecn no	dr	date		tolerances unless otherwise specified		title			
A	Released	J10-0185	T.I	2010-07-06		±0.2		0.3mm PITCH FPC CONNECTOR DOWN CONTACT TYPE			
B	Revised	J10-0268	T.I	2010-10-12		linear		MM			
C	Revised	ELX-J-01245-1	T.I	2012-08-31		±2'		scale			
dr		T.ISHISHITA		2012-08-31		FCJ		dwg no		sheet of size	
enr		H.Suzuki		2012-08-31		FCJ		10061122		6of7 A3	
chr		M.Kajjura		2012-08-31		FCJ		type		Product Customer Drawing	
appd								Rev.		C	

PRODUCT NO

10061122-**-**142HLF



FPC			
PARTS NAME	MATERIAL	QTY	REMARKS
6	BASE FILM	POLYAMDE	1
7	CONDUCTOR	COPPER FOIL	n [PLATING] ALL OVER Ni 4~12μm, Au 0.05~0.15μm
8	OVERLAY	POLYAMIDE	1
9	STIFFENER	POLYAMIDE	1

n: NO OF CONTACT

P/N	A	B	C	D	E
10061122-33142HLF	11.7	9.0	9.6	11.2	10.2
10061122-39142HLF	13.5	10.8	11.4	13.0	12.0
10061122-41142HLF	14.1	11.4	12.0	13.6	12.6
10061122-43142HLF	14.7	12.0	12.6	14.2	13.2
10061122-45142HLF	15.3	12.6	13.2	14.8	13.8
10061122-51142HLF	17.1	14.4	15.0	16.6	15.6

*For the corresponding position, please make an inquire to sales person in our company.

PARTS NAME	MATERIAL	QTY	REMARKS
1 HOUSING	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:BLACK
2 ACTUATOR	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:NATURAL
3 CONTACT A	COPPER ALLOY	(n-1)/2	[PLATING] ALL OVER Ni(WITH Ni BARRIER) CONTACT AREA: Au SOLDER TAIL AREA: Au
4 CONTACT B	COPPER ALLOY	(n+1)/2	[PLATING] ALL OVER Ni,Sn
5 FIXING TAB	COPPER ALLOY	2	[PLATING] ALL OVER Ni,Sn

n: NO OF CONTACT

NOTE
 1.CO-PLANARITY:0.08mmMAX
 2.THICKNESS OF A METAL MASK:0.1mm
 3.FPC
 Adhesive method of supporting tape shall be heat crimping method and thermosetting adhesive material shall be used.
 4.PRODUCT
 Recommended PCB layout and FPC area the same as 10064555-**-**210*LF(YLL-Upper contact type)
 5.OTHER
 This product meets European Union Directives and other country regulation as described in GS-22-008

mat'l. code		surface ISO 1302		tolerance ISO 406 ISO 1101		projection		product family 587F (YLL-D)		CODE JP	
lfr	description	ecn no	dr	date		tolerances unless otherwise specified		title		size	
A	Released	J10-0185	T.I	2010-07-06		± 0.2		0.3mm PITCH FPC CONNECTOR DOWN CONTACT TYPE		A3	
B	Revised	ELX-J-01245-1	T.I	2012-08-31		linear		MM			
C	Revised	ELX-J-14161-1	T.I	2013-03-05		± 2'		scale			
sheet index		revision sheet		dr T. SHISHITA 2013-03-05		enr H. Suzuki 2013-03-05		appd N. Sasame 2013-03-05		dwg no 10061122 sheet of 7 of 7	
										type Product Customer Drawing	
										Rev. C	